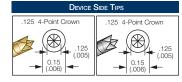
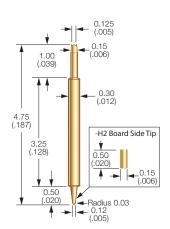
Semiconductor Probes 0.40MM PITCH

200-000940 Ргове





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 4.05mm (.160) Force per Contact: 26g (0.92 oz.) @ 0.70mm (.027) travel Device Compliance: 0.50mm (.020) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating

Spring: Music wire, gold plated

Device Side Contact: Full-hard beryllium copper, gold plated or Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

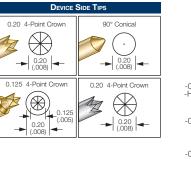
Typical Resistance: $< 80 \text{ m}\Omega$ Current Carrying Capacity: 1.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **R S R** @ 0.4mm pitch Characteristic Impedance: 44 Ω Time Delay: 21 pSec Loop Inductance: 0.95 nH Signal Pin to Return Capacitance: 0.48 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

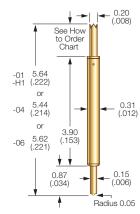
How to Order				
Part No.	Device Side Tip	PCB Side Tip	Spring Force	
200-000940-001	0.125 4-pt. Crown	Conical	26g	
200-000940-H1	0.125 4-pt. Crown	Conical	26g	
200-000940-H2	0.125 4-pt. Crown	Conical	26g	

H1 has the homogeneous alloy on the device side of the contact. Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

Specifications subject to change without notice. Dimensions in millimeters (inches)

623-0248 Ргове





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 01 & H1- 5.04mm (.198) 04 - 4.84mm (.190) 06 - 5.02mm (.198) Force per Contact: 25g (.88 oz.) @ 0.60mm (.024) travel Device Compliance: 0.40mm (.016) DUT Board Compliance: 0.20mm (.008)

Operating Temperature: -55°C to 120°C

(Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Brass, gold plated Spring: Music wire, gold plated

Device Side Contact:

01 & 06 Full-hard beryllium copper, gold plated

- 04 Carbon steel, gold plated
- H1 Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: 01 & H1 < 60 mΩ 04 & 06 < 50 mΩ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: $\bigcirc \bigcirc \bigcirc @ 0.4mm$ pitch Characteristic Impedance: 46 Ω Time Delay: 30 pSec Loop Inductance: 1.38 nH Signal Pin to Return Capacitance: 0.67 pF -1 dB Insertion Loss Bandwidth: > 13.2 GHz

How to Order					
Part No.	Device Side Tip	Plunger Length	PCB Side Tip		
623-0248-01	0.20 4-pt. Crown	0.87mm (.034)	Conical		
623-0248-04	Conical	0.67mm (.026)	Conical		
623-0248-06	0.125 4-pt. Crown	0.85mm (.033)	Conical		
623-0248-H1	0.20 4-pt. Crown	0.87 mm(.034)	Conical		

H1 has the homogeneous alloy on the device side of the contact.

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